

Composite Heat Sink for Enhanced Thermal Management

Track Code: 2019-MARC-68563

Categories:

- Electrical Engineering
- Materials and Manufacturing

Keywords:

- aerospace platform
- electronic systems
- power electronics
- Thermal

As electronic devices become more compact they require more efficient heat sinks to maintain high performance. Phase change materials (PCMs) are promising for transient thermal management, but have had limited use due to poor thermal conductivity.

Researchers at Purdue University have developed a composite PCM heat sink for passive thermal management of electronic systems. This technology utilizes novel geometries that provide a tunable design to address specific problems and power levels encountered with high power density devices. Furthermore, this technology extends the time to reach the cut-off temperature by about 36% at a reduced weight, making it advantageous for mobile devices, aerospace platforms, power electronics, or directed energy weapons.

Advantages:

- Tunable
- Extended time before overheating
- Light weight

Potential Applications:

- Mobile devices
- Aerospace platforms
- Power electronics

People:

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Intellectual Property:

Application Date: June 18, 2020

Type: Utility Patent

Country of Filing: United States

Patent Number: 11,243,032

Issue Date: February 8, 2022

Application Date: June 18, 2019

Type: Provisional-Patent

Country of Filing: United States

Patent Number: (None)

Issue Date: (None)

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